

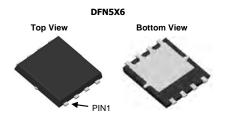
LH5036-VB Datasheet N-Channel 60 V (D-S) MOSFET

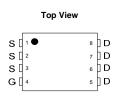
PRODUCT SUMMARY				
V _{DS} (V)	$V_{DS}(V)$ $R_{DS(on)}(\Omega)$			
60	0.003 at V _{GS} = 10 V	100		
	0.005 at V _{GS} = 4.5 V	85		

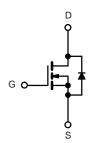
FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unless othe	rwise noted)			
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 25 °C	L-	100		
	T _C = 100 °C	I _D	85 ^a		
Pulsed Drain Current	I _{DM}	100	А		
Continuous Source Current (Diode Conduction)	I _S	80 ^a	1		
Avalanche Current		I _{AS}	70		
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	125	mJ	
Marianus Davis Dissination	T _C = 25 °C	P _D	136	W	
Maximum Power Dissipation	T _A = 25 °C	' D	3 ^b , 8.3 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	- R _{thJA}	15	18	°C/W	
Maximum Junction-to-Ambient	Steady State		40	50		
Maximum Junction-to-Case		R _{thJC}	0.85	1.1		

Notes

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. $t \le 10$ s.



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static			L			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	2	3	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
		V _{DS} = 60 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			Α
		V _{GS} = 10 V, I _D = 20 A		0.003		
D : 0	D	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008		0
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010		Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.005		
Forward Transconductance ^b	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		60		S
Dynamic				•		
Input Capacitance	C _{iss}			2650		
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		470		pF
Reverse Transfer Capacitance	C _{rss}			225		
Total Gate Charge ^c	Qg			47	70	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC
Gate-Drain Charge ^c	Q_{gd}			12		
Turn-On Delay Time ^c	t _{d(on)}			10	20	
Rise Time ^c	t _r	V_{DD} = 30 V, R_L = 0.6 Ω		15	25	no
Turn-Off Delay Time ^c	t _{d(off)}	$I_D\cong 50$ A, V_{GEN} = 10 V, R_g = 2.5 Ω		35	50	- ns
Fall Time ^c	t _f			20	30	
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)				
Pulsed Current	I _{SM}				60	Α
Diode Forward Voltage	V _{SD}	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V
Reverse Recovery Time	t _{rr}	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		45	100	ns

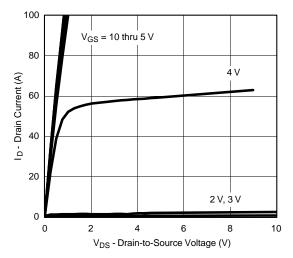
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

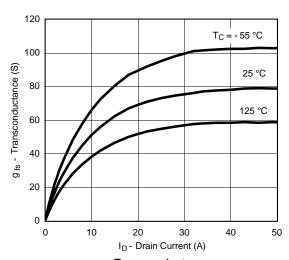
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



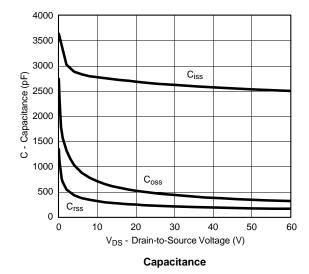
TYPICAL CHARACTERISTICS (25 °C unless noted)

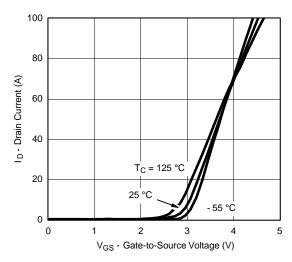


Output Characteristics

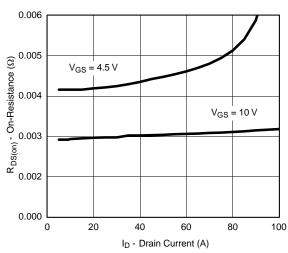


Transconductance

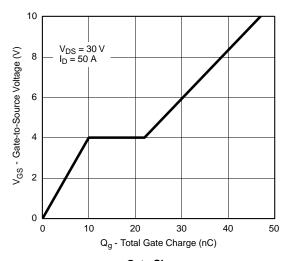




Transfer Characteristics



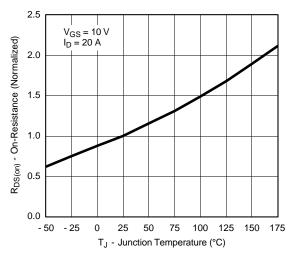
On-Resistance vs. Drain Current



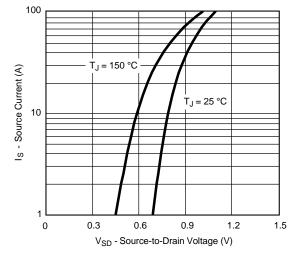
Gate Charge



TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

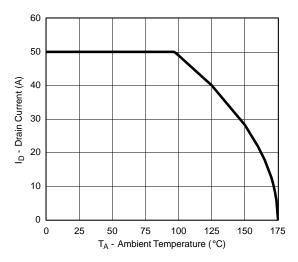


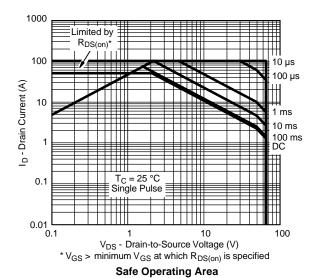
Source-Drain Diode Forward Voltage



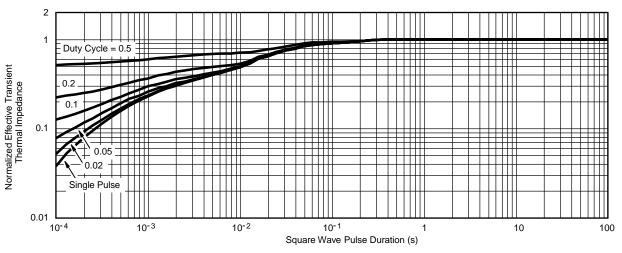
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THERMAL RATINGS





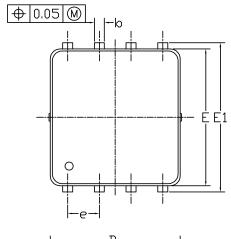
Maximum Drain Current vs. Ambient Temperature

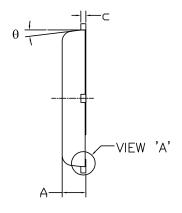


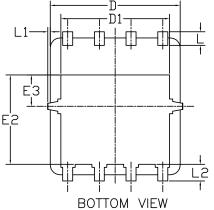
Normalized Thermal Transient Impedance, Junction-to-Case

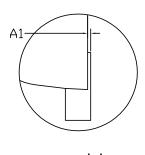


DFN5x6_8L_EP1_P PACKAGE OUTLIN



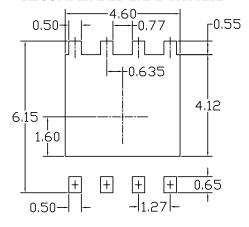






VIEW 'A' (SCALE 5:1)

RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES			
3 I MBOLS	MIN	NOM	MAX	MIN	NOM	MAX	
A	0.85	0. 95	1.00	0.033	0.037	0.039	
A1	0.00		0.05	0.000		0.002	
b	0.30	0.40	0.50	0.012	0.016	0.020	
с	0.15	0. 20	0. 25	0.006	0.008	0.010	
D	5. 10	5. 20	5. 30	0. 201	0. 205	0. 209	
D1	4. 25	4. 35	4. 45	0. 167	0. 171	0. 175	
Е	5. 45	5. 55	5. 65	0. 215	0. 219	0. 222	
E1	5. 95	6.05	6. 15	0. 234	0. 238	0. 242	
E2	3. 525	3.625	3. 725	0.139	0. 143	0. 147	
E3	1. 175	1. 275	1. 375	0.046	0.050	0.054	
e	1. 27 BSC			0.050 BSC			
L	0.45	0. 55	0.65	0.018	0.022	0.026	
L1	0		0. 15	0		0.006	
L2		0.68 REF			0.027 REF		
θ	0°		10°	0°		10°	

NOTE

- UNIT: mm 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.



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